REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	19JUL23	E. REYTA

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
   ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.

MATERIAL: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

2. BOARD MATERIAL:(USE CHECKED ITEMS)

   (X) ISOLA 370HR OR EQUIVALENT
   ( ) ISOLA-FR408HR OR EQUIVALENT
   ( ) ISOLA IS410
   ( ) MEGTRON 6
   ( ) NELCO-4000-13
   ( ) ROGERS 4350B
   ( ) ROGERS 3003
   ( ) ARLON 85N
   ( ) EM370D
   ( ) OTHER _____

3. ALL LAMINATES & BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103.(TG>170 DEGC TD>300 DEGC)
   UL FLAMMABILITY RATING 94V-0. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796/UL796F.
4. REFER TO IPC-6010 SERIES, CLASS 2 FOR FABRICATION. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2.
5. REFER TO LAMINATION DIAGRAM FOR OVERALL BOARD THICKNESS, TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING
   PROCESSES. FINISHED THICKNESS MEASURED FROM TOP COPPER TO BOTTOM COPPER.
6. BOW & TWIST NOT TO EXCEED 0.0075 INCHES (0.75%) PER LINEAR INCH AND SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
7. ACCEPTABILITY PER ADI SPECIFICATION TST00115.

TOOLING:

8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC
   THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST
   MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP,
   TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.
9. FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.
   ( ) FILLETS ALLOWED
   (X) FILLETS NOT ALLOWED
10. THIEVING:
   ( ) VENDOR MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM
   0.100 INCH CLEARANCE FROM ALL COPPER FEATURES.
   (X) VENDOR MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.
11. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003 INCHES.

FINISH:

12. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.005 INCHES DTP,UNLESS SPECIFIED.
   MINIMUM BARREL PLATING OF 0.001 INCHES. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO
   HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.
13. PLATING SPECIFICATION:
   (X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIRMENTS
   THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER
   WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.
14. SURFACE FINISH:
   (X) IMMERSION GOLD (ENIG) 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552
   ( ) OSP (ORGANIC SOLDERABILITY PRESERVATIVE)
   ( ) IMMERSION SILVER
   ( ) SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE
   BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL
   ( ) EDGE CONNECTOR FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES(.0001") OF LOW STRESS
   NICKEL UNDER 30 MICRO-INCHES (.0003") OF GOLD
   ( ) OTHER:

15. SOLDERMASK:
   SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.
   IF PRESENT,DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.
   (X) LPI
   ( ) OTHER_____

   COLOR
   ( ) GREEN
   (X) OTHER___BLUE__

16. APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.
   (X) WHITE
   ( ) OTHER

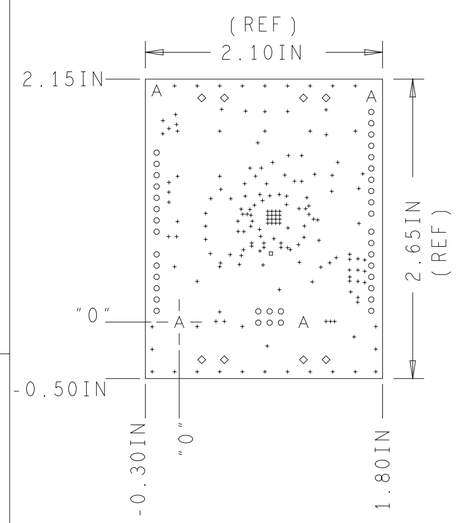
TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.
   THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE
   OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING
   CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES
   IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.

MISCELLANEOUS:

19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN
   USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED
   WITH NON-CONDUCTIVE EPOXY.
20. FOR VIA FILL INFORMATION REFER TO DRILL CHART:
   ( ) NON-CONDUCTIVE EPOXY FILL ALL 0.XXXX INCHES DRILLED VIAS
   ( ) COPPER FILL ALL 0.XXXX INCHES DRILLED VIAS
21. INTENTIONAL SHORTS:
   IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN
   ADI APPROVAL IS REQUIRED.
22. PEMNUTS:
   ( ) PEMNUTS TO BE INSTALLED BY FABRICATOR
   ( ) PEMNUTS NOT TO BE INSTALLED BY FABRICATOR
   (X) NOT APPLICABLE
23. MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK
   ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:
   A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS(IF APPLICABLE)
   B. DATE CODE
   C. LOT NUMBER
   D. MANUFACTURER LOGO
24. MINIMUM DESIGN LINE WIDTH IS .008 INCH.
25. MINIMUM DESIGN LINE SPACING IS .008 INCH.
26. BOARDS TO BE SHIPPED SINGULATED AFTER FABRICATION PROCESS
   SMOOTHEN EDGES AND FREE FROM BURRS AFTER DEPANELIZATION PROCESS

FAB NOTES REVISION: 2ND NOVEMBER 2022



HOLE TOLERANCE

UNLESS SPECIFIED
PLATED: +/- .003
NON PLATED: +/- .002

FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	10.0	PLATED	172	DIA MAX
▫	15.0	PLATED	1	
○	45.0	PLATED	38	
◇	50.0	PLATED	8	
A	125.0	NON-PLATED	4	

TENTED VIA

LAMINATION DIAGRAM

LAYER NUMBER	LAYER NAME	FINISHED CU WEIGHT (OZ)	DIELECTRIC THICKNESS (INCH)	MATERIALS
1	TOP	0.5		FINAL CU(THICKNESS AFTER PLATING)
			0.0063	ISOLA 370HR/EQUIVALENT
2	L2_GND	1		CU CLAD
			0.044	ISOLA 370HR/EQUIVALENT
3	L3_GND	1		CU CLAD
			0.0063	ISOLA 370HR/EQUIVALENT
4	BOTTOM	0.5		FINAL CU(THICKNESS AFTER PLATING)

THE FINISHED PCB THICKNESS TO BE: 0.062" +/-0.006"

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS .XX +-.010 .XXX +-.005 .XXXX +-.0050 FRACTIONS +-1/32 ANGLES +- 2	APPROVAL	DATE
	TEMPLATE ENGINEER BILLY PHILLIPS	07APR21
	HARDWARE SERVICES BOB MACDONALD	07APR21
	HARDWARE SYSTEMS DAVE WILLIAMS	07APR21
MATERIAL	TEST ENGINEER N/A	N/A
	COMPONENT ENGINEER ADGT LIBRARY	19JUL23
	TEST PROCESS N/A	N/A
	HARDWARE RELEASE C. PASIA	19JUL23
FINISH	DESIGNER C. PASIA	19JUL23
	PTD ENGINEER E. REYTA	19JUL23
	CHECKER N/A	N/A
DO NOT SCALE DWG		

ANALOG DEVICES

WWM
DIVISION
804 WOBURN STREET
WILMINGTON, MA 01887

TITLE
FABRICATION
EV-FLOWMETER-ARDZ

SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	09-079878	A

SCALE 1/1 SHEET 1 OF 1